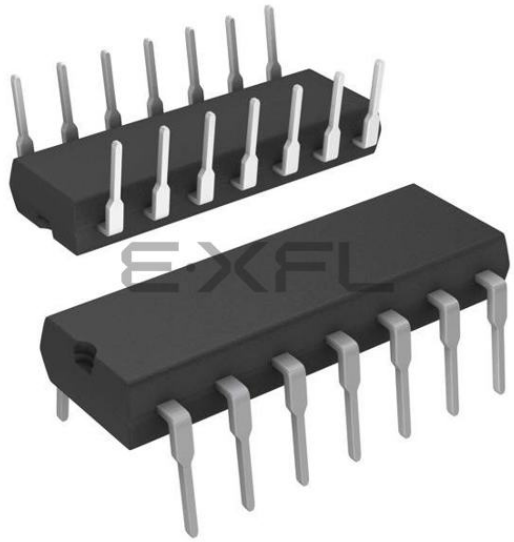

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	11
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	14-DIP (0.300", 7.62mm)
Supplier Device Package	14-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1825-i-p

FIGURE 1: 14-PIN DIAGRAM FOR PIC16(L)F1825

PDIP, SOIC, TSSOP

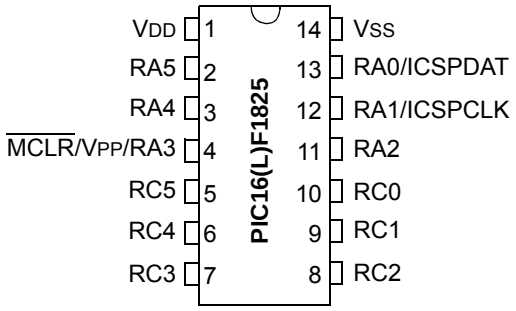


FIGURE 2: 16-PIN DIAGRAM FOR PIC16(L)F1825

QFN, UQFN

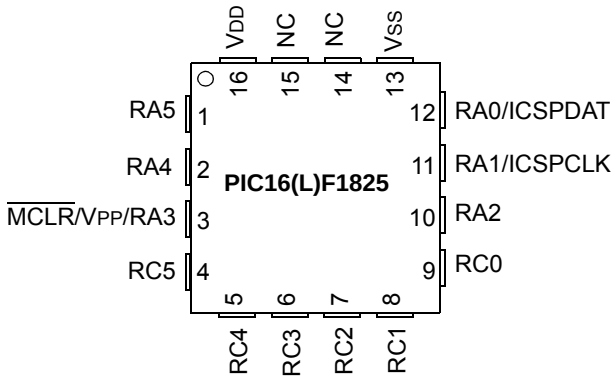


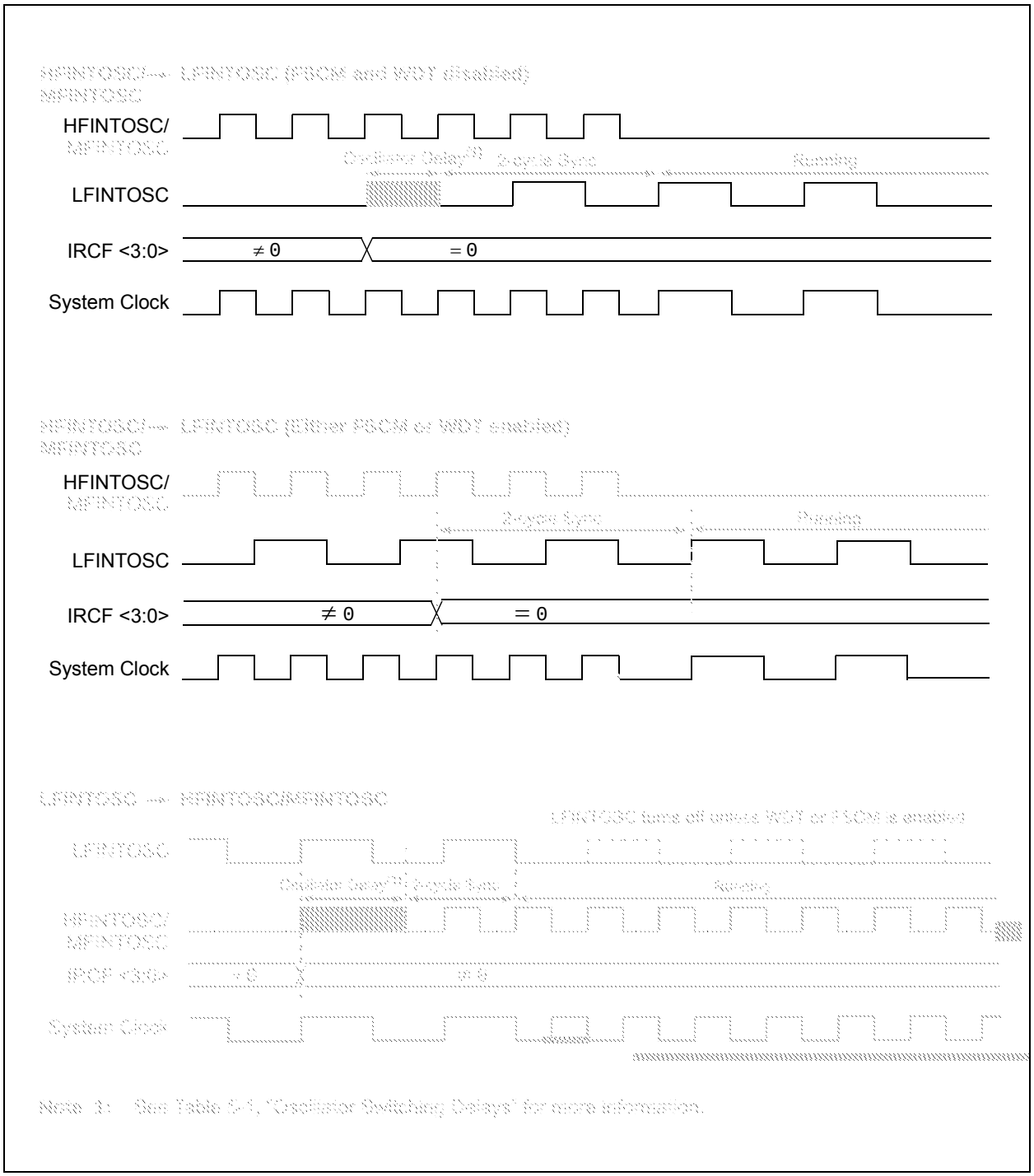
TABLE 1-3: PIC16(L)F1829 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RC2/AN6/CPS6/C12IN2-/ P1D(1,2)/P2B(1,2)/MDCIN1	RC2	TTL	CMOS	General purpose I/O.
	AN6	AN	—	A/D Channel 6 input.
	CPS6	AN	—	Capacitive sensing input 6.
	C12IN2-	AN	—	Comparator C1 or C2 negative input.
	P1D	—	CMOS	PWM output.
	P2B	—	CMOS	PWM output.
	MDCIN1	ST	—	Modulator Carrier Input 1.
RC3/AN7/CPS7/C12IN3-/ P2A(1,2)/CCP2(1,2)/P1C(1,2)/ MDMIN	RC3	TTL	CMOS	General purpose I/O.
	AN7	AN	—	A/D Channel 7 input.
	CPS7	AN	—	Capacitive sensing input 7.
	C12IN3-	AN	—	Comparator C1 or C2 negative input.
	P2A	—	CMOS	PWM output.
	CCP2	AN	—	Capture/Compare/PWM2.
	P1C	—	CMOS	PWM output.
	MDMIN	ST	—	Modulator source input.
RC4/C2OUT/SRNQ/P1B/TX(1)/ CK(1)/MDOUT	RC4	TTL	CMOS	General purpose I/O.
	C2OUT	—	CMOS	Comparator C2 output.
	SRNQ	—	CMOS	SR Latch inverting output.
	P1B	—	CMOS	PWM output.
	TX	—	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
	MDOUT	—	CMOS	Modulator output.
RC5/P1A/CCP1/DT(1)/RX(1)/ MDCIN2	RC5	TTL	CMOS	General purpose I/O.
	P1A	—	CMOS	PWM output.
	CCP1	ST	CMOS	Capture/Compare/PWM1.
	RX	ST	—	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
	MDCIN2	ST	—	Modulator Carrier Input 2.
RC6/AN8/CPS8/CCP4/$\overline{SS1}$	RC6	TTL	CMOS	General purpose I/O.
	AN8	AN	—	A/D Channel 8 input.
	CPS8	AN	—	Capacitive sensing input 8.
	CCP4	AN	—	Capture/Compare/PWM4.
	$\overline{SS1}$	ST	—	Slave Select input.
RC7/AN9/CPS9/SDO1	RC7	TTL	CMOS	General purpose I/O.
	AN9	AN	—	A/D Channel 9 input.
	CPS9	AN	—	Capacitive sensing input 9.
	SDO1	—	CMOS	SPI data output.
VDD	VDD	Power	—	Positive supply.
VSS	VSS	Power	—	Ground reference.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C™ = Schmitt Trigger input with I^2C levels
HV = High Voltage XTAL = Crystal

Note 1: Pin functions can be moved using the APFCON0 or APFCON1 register.
2: Default function location.

FIGURE 5-7: INTERNAL OSCILLATOR SWITCH TIMING



Note 1: See Table 5-1, 'Oscillator Switching Delays' for more information.

7.0 RESETS

There are multiple ways to reset this device:

- Power-on Reset (POR)
- Brown-out Reset (BOR)
- $\overline{\text{MCLR}}$ Reset
- WDT Reset
- RESET instruction
- Stack Overflow
- Stack Underflow
- Programming mode exit

To allow V_{DD} to stabilize, an optional power-up timer can be enabled to extend the Reset time after a BOR or POR event.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 7-1.

FIGURE 7-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT

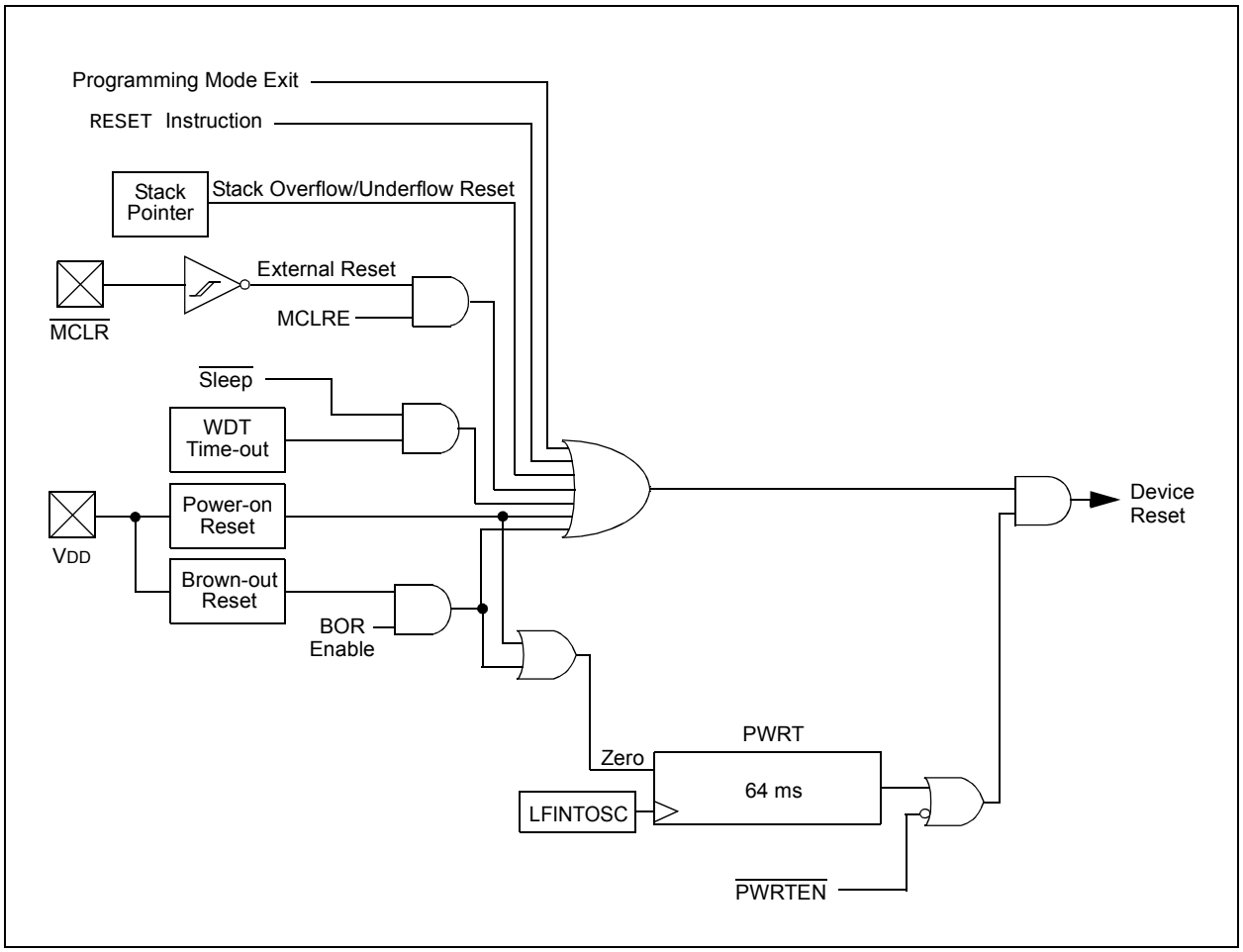
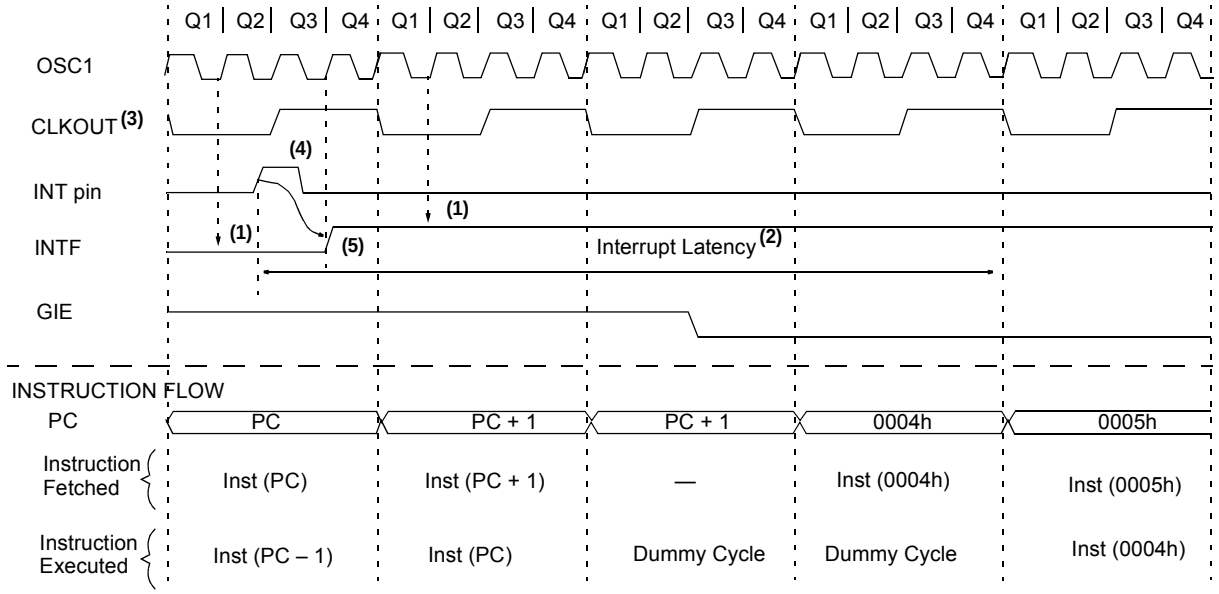


FIGURE 8-3: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-5 TCY. Synchronous latency = 3-4 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT not available in all oscillator modes.

4: For minimum width of INT pulse, refer to AC specifications in **Section 30.0 "Electrical Specifications"**.

5: INTF is enabled to be set any time during the Q4-Q1 cycles.

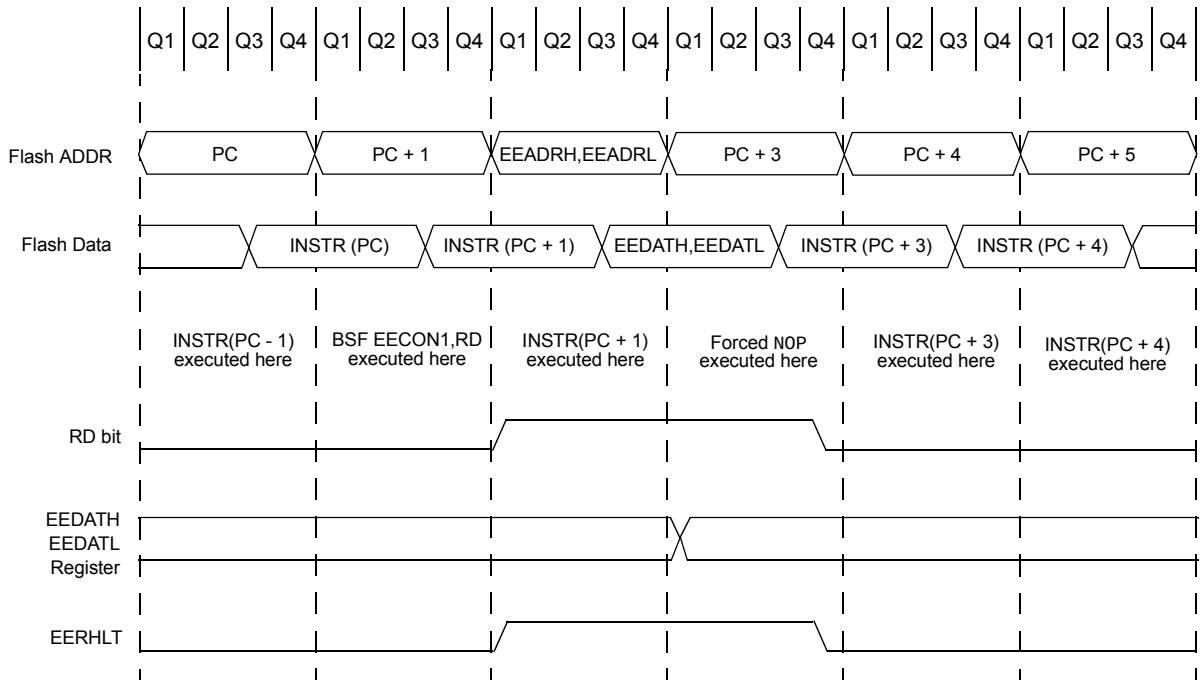
EXAMPLE 11-2: DATA EEPROM WRITE

Required Sequence

```
BANKSEL  EEADRL          ;
MOVLW    DATA_EE_ADDR    ;
MOVWF    EEADRL          ;Data Memory Address to write
MOVLW    DATA_EE_DATA    ;
MOVWF    EEDATL          ;Data Memory Value to write
BCF      EECON1, CFGS    ;Deselect Configuration space
BCF      EECON1, EEPGD   ;Point to DATA memory
BSF      EECON1, WREN    ;Enable writes

BCF      INTCON, GIE     ;Disable INTs.
MOVLW    55h             ;
MOVWF    EECON2          ;Write 55h
MOVLW    0AAh            ;
MOVWF    EECON2          ;Write AAh
BSF      EECON1, WR      ;Set WR bit to begin write
BSF      INTCON, GIE     ;Enable Interrupts
BCF      EECON1, WREN    ;Disable writes
BTFSC    EECON1, WR      ;Wait for write to complete
GOTO     $-2             ;Done
```

FIGURE 11-1: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



14.3 FVR Control Registers

REGISTER 14-1: FVRCON: FIXED VOLTAGE REFERENCE CONTROL REGISTER

R/W-0/0	R-q/q	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
FVREN	FVRRDY(1)	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **FVREN:** Fixed Voltage Reference Enable bit
0 = Fixed Voltage Reference is disabled
1 = Fixed Voltage Reference is enabled

bit 6 **FVRRDY:** Fixed Voltage Reference Ready Flag bit(1)
0 = Fixed Voltage Reference output is not ready or not enabled
1 = Fixed Voltage Reference output is ready for use

bit 5 **TSEN:** Temperature Indicator Enable bit
0 = Temperature indicator is disabled
1 = Temperature indicator is enabled

bit 4 **TSRNG:** Temperature Indicator Range Selection bit(3)
0 = $V_{OUT} = V_{DD} - 2V_T$ (Low Range)
1 = $V_{OUT} = V_{DD} - 4V_T$ (High Range)

bit 3-2 **CDAFVR<1:0>:** Comparator and DAC Fixed Voltage Reference Selection bit
00 = Comparator and DAC Fixed Voltage Reference Peripheral output is off
01 = Comparator and DAC Fixed Voltage Reference Peripheral output is 1x (1.024V)
10 = Comparator and DAC Fixed Voltage Reference Peripheral output is 2x (2.048V)(2)
11 = Comparator and DAC Fixed Voltage Reference Peripheral output is 4x (4.096V)(2)

bit 1-0 **ADFVR<1:0>:** ADC Fixed Voltage Reference Selection bit
00 = ADC Fixed Voltage Reference Peripheral output is off
01 = ADC Fixed Voltage Reference Peripheral output is 1x (1.024V)
10 = ADC Fixed Voltage Reference Peripheral output is 2x (2.048V)(2)
11 = ADC Fixed Voltage Reference Peripheral output is 4x (4.096V)(2)

Note 1: FVRRDY is always '1' on devices with the LDO (PIC16F1825/9).
2: Fixed Voltage Reference output cannot exceed V_{DD}.
3: See **Section 15.0 "Temperature Indicator Module"** for additional information.

TABLE 14-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE FIXED VOLTAGE REFERENCE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>		142

Legend: Shaded cells are unused by the Fixed Voltage Reference module.

REGISTER 23-1: MDCON: MODULATION CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-1/1	R/W-0/0	R-0/0	U-0	U-0	R/W-0/0
MDEN	MDOE	MDSLR	MDOPOL	MDOUT	—	—	MDBIT
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **MDEN:** Modulator Module Enable bit
- 1 = Modulator module is enabled and mixing input signals
- 0 = Modulator module is disabled and has no output

bit 6 **MDOE:** Modulator Module Pin Output Enable bit
- 1 = Modulator pin output enabled
- 0 = Modulator pin output disabled

bit 5 **MDSLR:** MDOUT Pin Slew Rate Limiting bit
- 1 = MDOUT pin slew rate limiting enabled
- 0 = MDOUT pin slew rate limiting disabled

bit 4 **MDOPOL:** Modulator Output Polarity Select bit
- 1 = Modulator output signal is inverted
- 0 = Modulator output signal is not inverted

bit 3 **MDOUT:** Modulator Output bit

Displays the current output value of the modulator module.(1)

bit 2-1 **Unimplemented:** Read as ‘0’

bit 0 **MDBIT:** Allows software to manually set modulation source input to module(2)
- 1 = Modulator uses High Carrier source
- 0 = Modulator uses Low Carrier source

Note 1: The modulated output frequency can be greater and asynchronous from the clock that updates this register bit, the bit value may not be valid for higher speed modulator or carrier signals.

2: MDBIT must be selected as the modulation source in the MDSRC register for this operation.

24.0 CAPTURE/COMPARE/PWM MODULES

The Capture/Compare/PWM module is a peripheral which allows the user to time and control different events, and to generate Pulse-Width Modulation (PWM) signals. In Capture mode, the peripheral allows the timing of the duration of an event. The Compare mode allows the user to trigger an external event when a predetermined amount of time has expired. The PWM mode can generate Pulse-Width Modulated signals of varying frequency and duty cycle.

This family of devices contains two Enhanced Capture/Compare/PWM modules (ECCP1 and ECCP2) and two standard Capture/Compare/PWM modules (CCP3 and CCP4).

The Capture and Compare functions are identical for all four CCP modules (ECCP1, ECCP2, CCP3 and CCP4). The only differences between CCP modules are in the Pulse-Width Modulation (PWM) function. The standard PWM function is identical in modules, CCP3 and CCP4. In CCP modules ECCP1 and ECCP2, the Enhanced PWM function has slight variations from one another. Full-Bridge ECCP modules have four available I/O pins while Half-Bridge ECCP modules only have two available I/O pins. See Table 24-1 for more information.

Note 1: In devices with more than one CCP module, it is very important to pay close attention to the register names used. A number placed after the module acronym is used to distinguish between separate modules. For example, the CCP1CON and CCP2CON control the same operational aspects of two completely different CCP modules.

2: Throughout this section, generic references to a CCP module in any of its operating modes may be interpreted as being equally applicable to ECCP1, ECCP2, CCP3 and CCP4. Register names, module signals, I/O pins, and bit names may use the generic designator 'x' to indicate the use of a numeral to distinguish a particular module, when required.

TABLE 24-1: PWM RESOURCES

Device Name	ECCP1	ECCP2	CCP3	CCP4
PIC16(L)F1825/9	Enhanced PWM Full-Bridge	Enhanced PWM Half-Bridge	Standard PWM	Standard PWM

24.4.6 PWM STEERING MODE

In Single Output mode, PWM steering allows any of the PWM pins to be the modulated signal. Additionally, the same PWM signal can be simultaneously available on multiple pins.

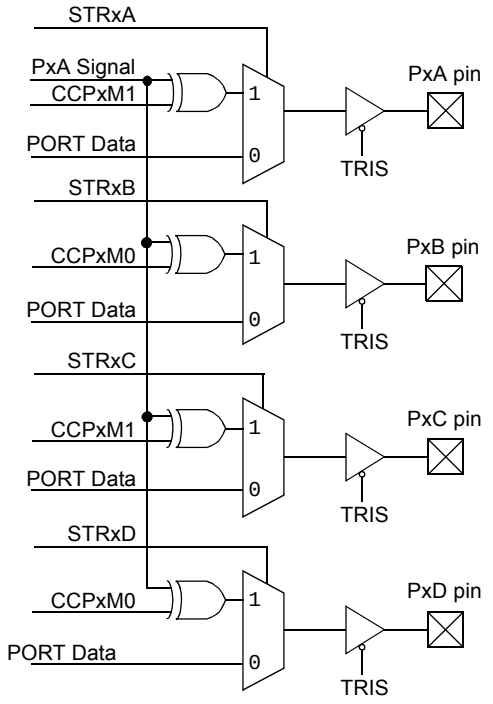
Once the Single Output mode is selected (CCPxM<3:2> = 11 and PxM<1:0> = 00 of the CCPxCON register), the user firmware can bring out the same PWM signal to one, two, three or four output pins by setting the appropriate STRx<D:A> bits of the PSTRxCON register, as shown in Table 24-8.

Note:	The associated TRIS bits must be set to output ('0') to enable the pin output driver in order to see the PWM signal on the pin.

While the PWM Steering mode is active, CCPxM<1:0> bits of the CCPxCON register select the PWM output polarity for the Px<D:A> pins.

The PWM auto-shutdown operation also applies to PWM Steering mode as described in **Section 24.4.3 "Enhanced PWM Auto-shutdown mode"**. An auto-shutdown event will only affect pins that have PWM outputs enabled.

FIGURE 24-18: SIMPLIFIED STEERING BLOCK DIAGRAM



Note 1: Port outputs are configured as shown when the CCPxCON register bits PxM<1:0> = 00 and CCPxM<3:2> = 11.

2: Single PWM output requires setting at least one of the STRx bits.

25.4 I²C MODE OPERATION

All MSSPx I²C communication is byte oriented and shifted out MSb first. Six SFR registers and two interrupt flags interface the module with the PIC® microcontroller and user software. Two pins, SDAx and SCLx, are exercised by the module to communicate with other external I²C devices.

25.4.1 BYTE FORMAT

All communication in I²C is done in 9-bit segments. A byte is sent from a master to a slave or vice-versa, followed by an Acknowledge bit sent back. After the 8th falling edge of the SCLx line, the device outputting data on the SDAx changes that pin to an input and reads in an acknowledge value on the next clock pulse.

The clock signal, SCLx, is provided by the master. Data is valid to change while the SCLx signal is low, and sampled on the rising edge of the clock. Changes on the SDAx line while the SCLx line is high define special conditions on the bus, explained below.

25.4.2 DEFINITION OF I²C TERMINOLOGY

There is language and terminology in the description of I²C communication that have definitions specific to I²C. That word usage is defined below and may be used in the rest of this document without explanation. This table was adapted from the Philips I²C specification.

25.4.3 SDAx AND SCLx PINS

Selection of any I²C mode with the SSPEN bit set, forces the SCLx and SDAx pins to be open-drain. These pins should be set by the user to inputs by setting the appropriate TRIS bits.

Note: Data is tied to output zero when an I²C mode is enabled.

25.4.4 SDAx HOLD TIME

The hold time of the SDAx pin is selected by the SDAHT bit of the SSPxCON3 register. Hold time is the time SDAx is held valid after the falling edge of SCLx. Setting the SDAHT bit selects a longer 300 ns minimum hold time and may help on buses with large capacitance.

TABLE 25-2: I²C BUS TERMS

TERM	Description
Transmitter	The device which shifts data out onto the bus.
Receiver	The device which shifts data in from the bus.
Master	The device that initiates a transfer, generates clock signals and terminates a transfer.
Slave	The device addressed by the master.
Multi-master	A bus with more than one device that can initiate data transfers.
Arbitration	Procedure to ensure that only one master at a time controls the bus. Winning arbitration ensures that the message is not corrupted.
Synchronization	Procedure to synchronize the clocks of two or more devices on the bus.
Idle	No master is controlling the bus, and both SDAx and SCLx lines are high.
Active	Any time one or more master devices are controlling the bus.
Addressed Slave	Slave device that has received a matching address and is actively being clocked by a master.
Matching Address	Address byte that is clocked into a slave that matches the value stored in SSPxADD.
Write Request	Slave receives a matching address with R/$\overline{W}$ bit clear, and is ready to clock in data.
Read Request	Master sends an address byte with the R/$\overline{W}$ bit set, indicating that it wishes to clock data out of the Slave. This data is the next and all following bytes until a Restart or Stop.
Clock Stretching	When a device on the bus hold SCLx low to stall communication.
Bus Collision	Any time the SDAx line is sampled low by the module while it is outputting and expected high state.

25.6.13.2 Bus Collision During a Repeated Start Condition

During a Repeated Start condition, a bus collision occurs if:

a) A low level is sampled on SDAx when SCLx goes from low level to high level. (CASE 1)

b) SCLx goes low before SDAx is asserted low, indicating that another master is attempting to transmit a data '1'. (CASE 2)

When the user releases SDAx and the pin is allowed to float high, the BRG is loaded with SSPxADD and counts down to zero. The SCLx pin is then deasserted and when sampled high, the SDAx pin is sampled.

If SDAx is low, a bus collision has occurred (i.e., another master is attempting to transmit a data '0' (Figure 25-36). If SDAx is sampled high, the BRG is reloaded and begins counting. If SDAx goes from high-to-low before the BRG times out, no bus collision occurs because no two masters can assert SDAx at exactly the same time.

If SCLx goes from high-to-low before the BRG times out and SDAx has not already been asserted, a bus collision occurs. In this case, another master is attempting to transmit a data '1' during the Repeated Start condition (Figure 25-37).

If, at the end of the BRG time-out, both SCLx and SDAx are still high, the SDAx pin is driven low and the BRG is reloaded and begins counting. At the end of the count, regardless of the status of the SCLx pin, the SCLx pin is driven low and the Repeated Start condition is complete.

FIGURE 25-36: BUS COLLISION DURING A REPEATED START CONDITION (CASE 1)

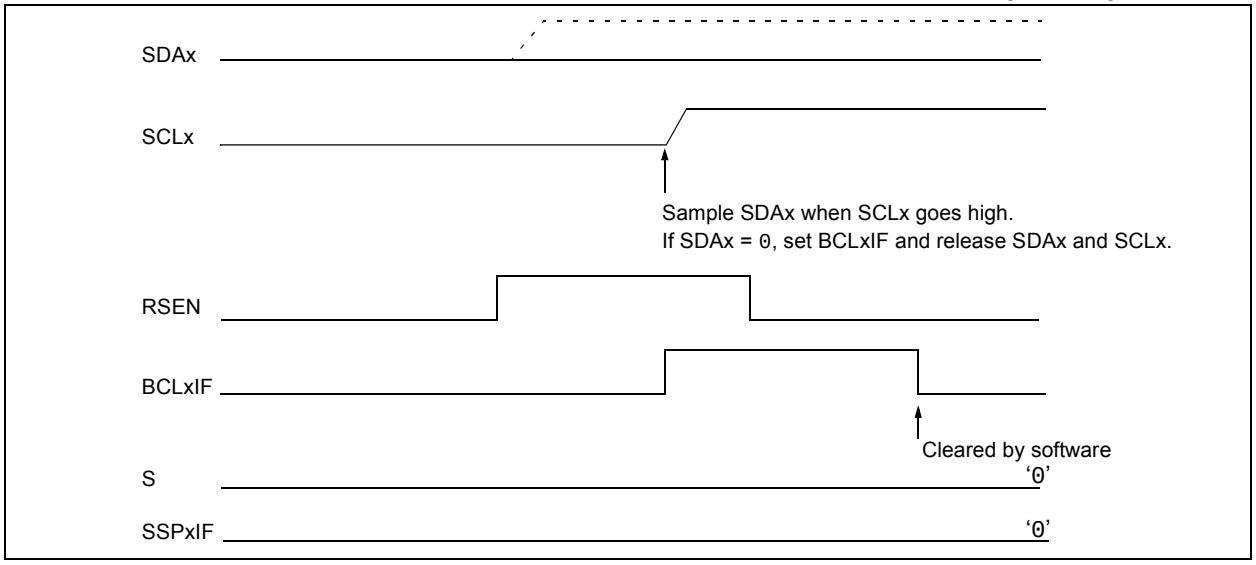


FIGURE 25-37: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)

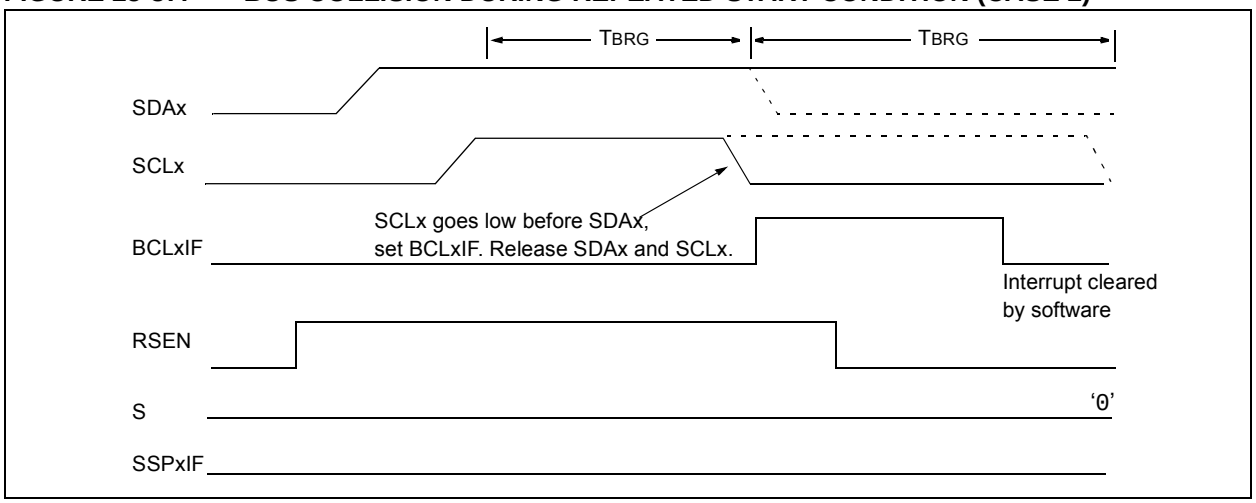
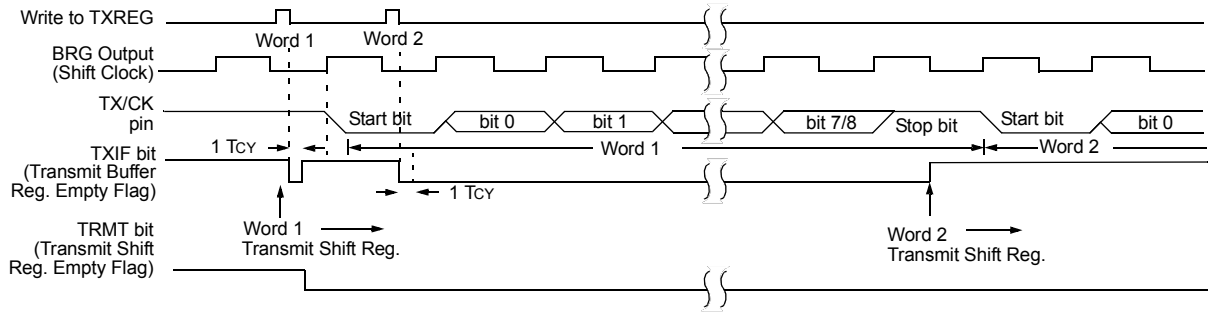


FIGURE 26-4: ASYNCHRONOUS TRANSMISSION (BACK-TO-BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 26-1: SUMMARY OF REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
APFCON0	RXDTSEL	SDO1SEL(2)	SS1SEL(2)	—	T1GSEL	TXCKSEL	—	—	118
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	292
INLVLA(3)	—	—	INLVLA5	INLVLA4	INLVLA3	INLVLA2	INLVLA1	INLVLA0	124
INLVLB(1)	INLVLB7	INLVLB6	INLVLB5	INLVLB4	—	—	—	—	129
INLVLC	INLVLC7(1)	INLVLC6(1)	INLVLC5	INLVLC4	INLVLC3	INLVLC2	INLVLC1	INLVLC0	135
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	87
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	88
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	92
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	291
SPBRGL	SPBRG<7:0>								293*
SPBRGH	SPBRG<15:8>								293*
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	122
TRISB(1)	TRISB7	TRISB6	TRISB5	TRISB4	—	—	—	—	128
TRISC	TRISC7(1)	TRISC6(1)	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	133
TXREG	EUSART Transmit Data Register								283
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	290

Legend: — Unimplemented location, read as '0'. Shaded cells are not used for asynchronous transmission.
* Page provides register information.

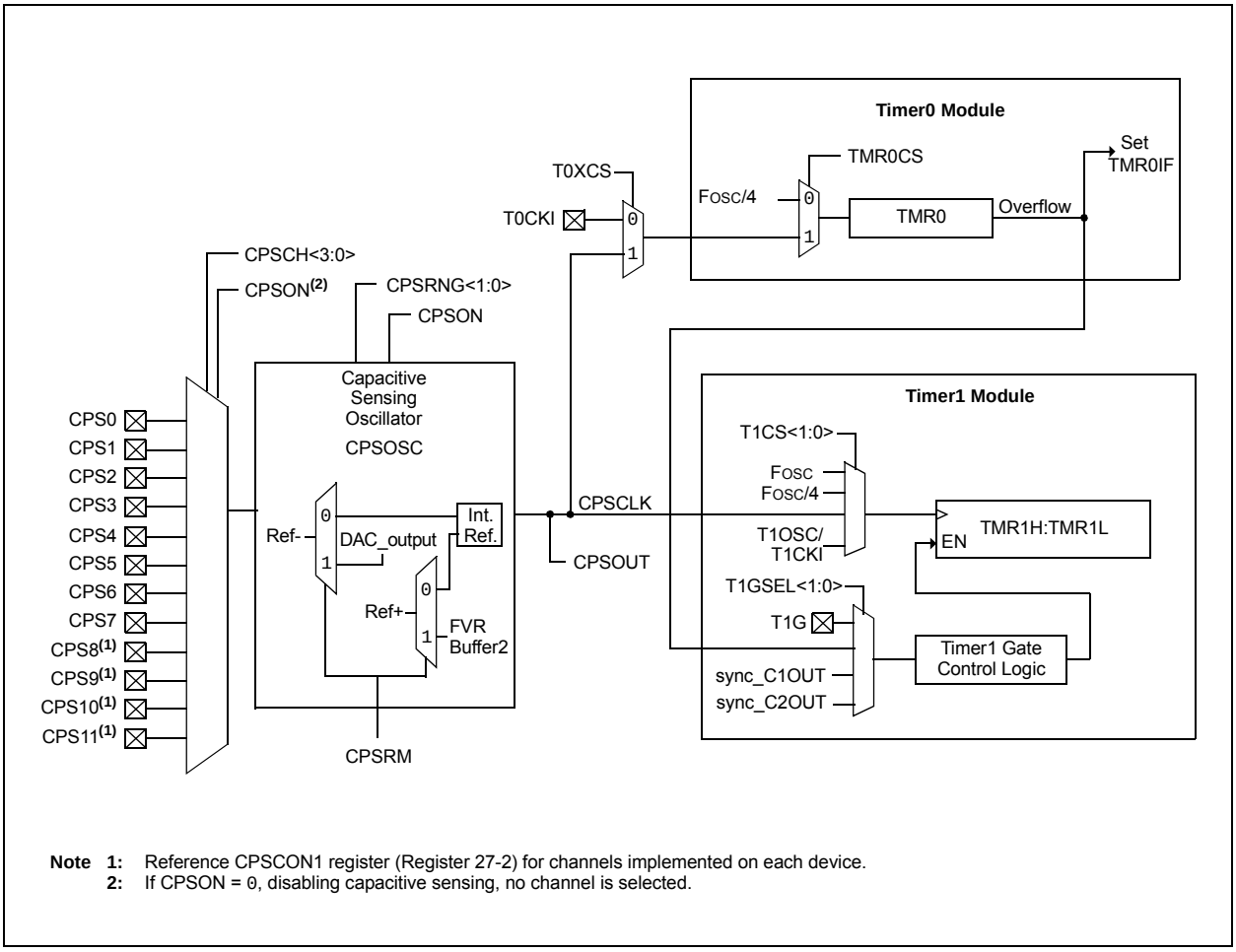
Note 1: PIC16(L)F1829 only.
2: PIC16(L)F1825 only.
3: Unshaded cells apply to PIC16(L)F1825 only.

27.0 CAPACITIVE SENSING (CPS) MODULE

The Capacitive Sensing (CPS) module allows for an interaction with an end user without a mechanical interface. In a typical application, the CPS module is attached to a pad on a Printed Circuit Board (PCB), which is electrically isolated from the end user. When the end user places their finger over the PCB pad, a capacitive load is added, causing a frequency shift in the CPS module. The CPS module requires software and at least one timer resource to determine the change in frequency. Key features of this module include:

- Analog MUX for monitoring multiple inputs
- Capacitive sensing oscillator
- Multiple current modes
- Multiple voltage reference modes
- Multiple timer resources
- Software control
- Operation during Sleep

FIGURE 27-1: CAPACITIVE SENSING BLOCK DIAGRAM



Note 1: Reference CPSCON1 register (Register 27-2) for channels implemented on each device.
2: If CPSON = 0, disabling capacitive sensing, no channel is selected.

FIGURE 30-16: SPI MASTER MODE TIMING (CKE = 0, SMP = 0)

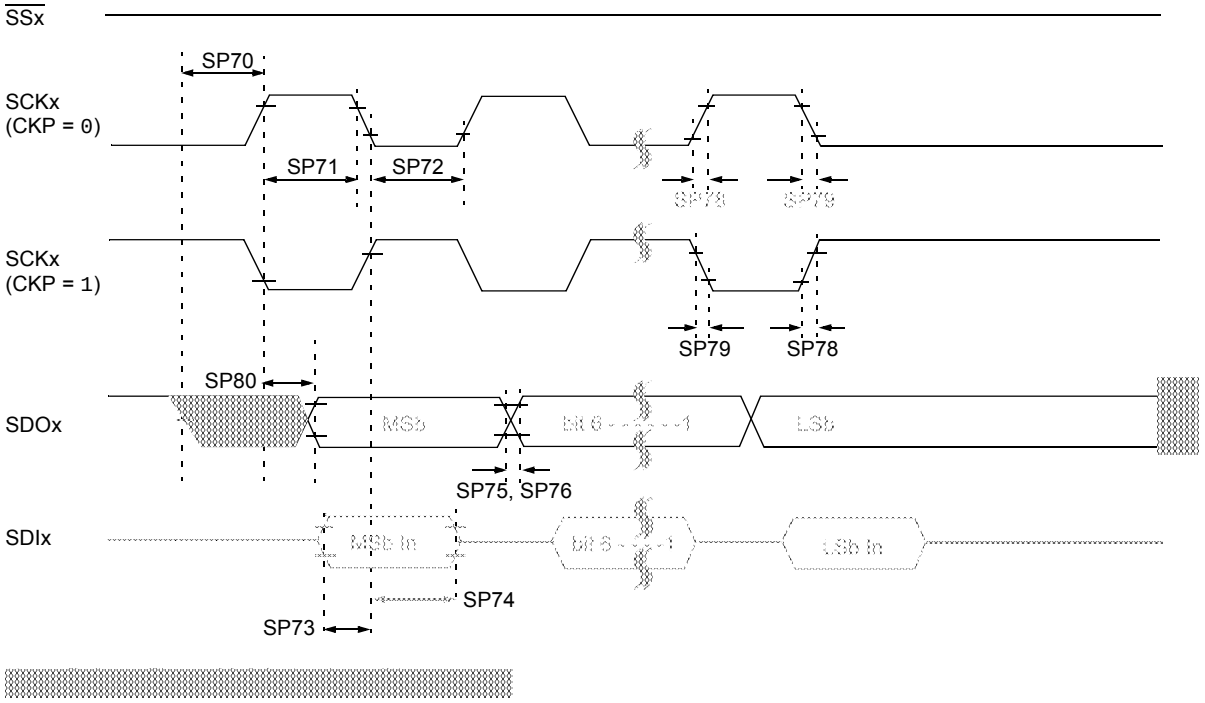
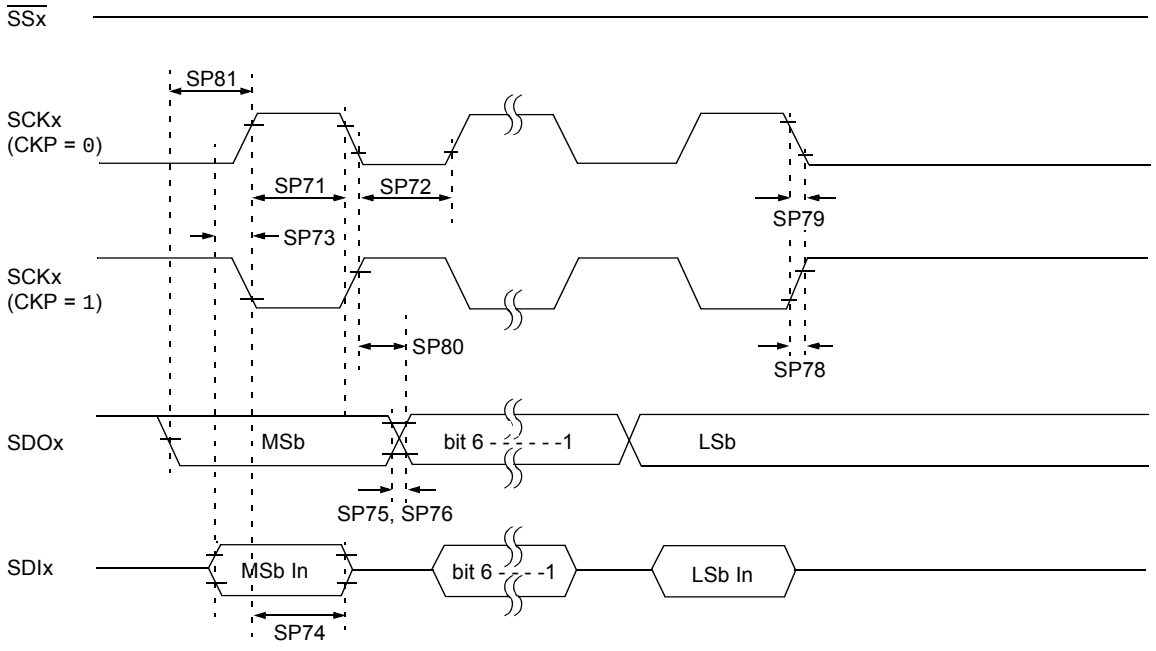


FIGURE 30-17: SPI MASTER MODE TIMING (CKE = 1, SMP = 1)



Note: Refer to Figure 30-5 for load conditions.

TABLE 30-19: DC CHARACTERISTICS FOR PIC16F1825/9-H (High Temp.)

PIC16F1825/9			Standard Operating Conditions: (unless otherwise stated) Operating Temperature: -40°C ≤ TA ≤ +150°C for High Temperature				
Param No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Condition**
D001	VDD	Supply Voltage	2.5	—	5.5	V	FOSC ≤ 32 MHz **(Note 2)**
D002*	VDR	RAM Data Retention Voltage(1)	2.1	—	5.5	V	Device in Sleep mode
D003	VADFVR	Fixed Voltage Reference Voltage for ADC	-10	—	8	%	1.024V, VDD ≥ 2.5V 2.048V, VDD ≥ 2.5V 4.096V, VDD ≥ 4.75V
D003A	VCDAFVR	Fixed Voltage Reference Voltage for ADC	-13	—	9	%	1.024V, VDD ≥ 2.5V 2.048V, VDD ≥ 2.5V 4.096V, VDD ≥ 4.75V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: PLL required for 32 MHz operation.

FIGURE 31-1: IDD, LP OSCILLATOR MODE (FOSC = 32 kHz), PIC16LF1825/9 ONLY

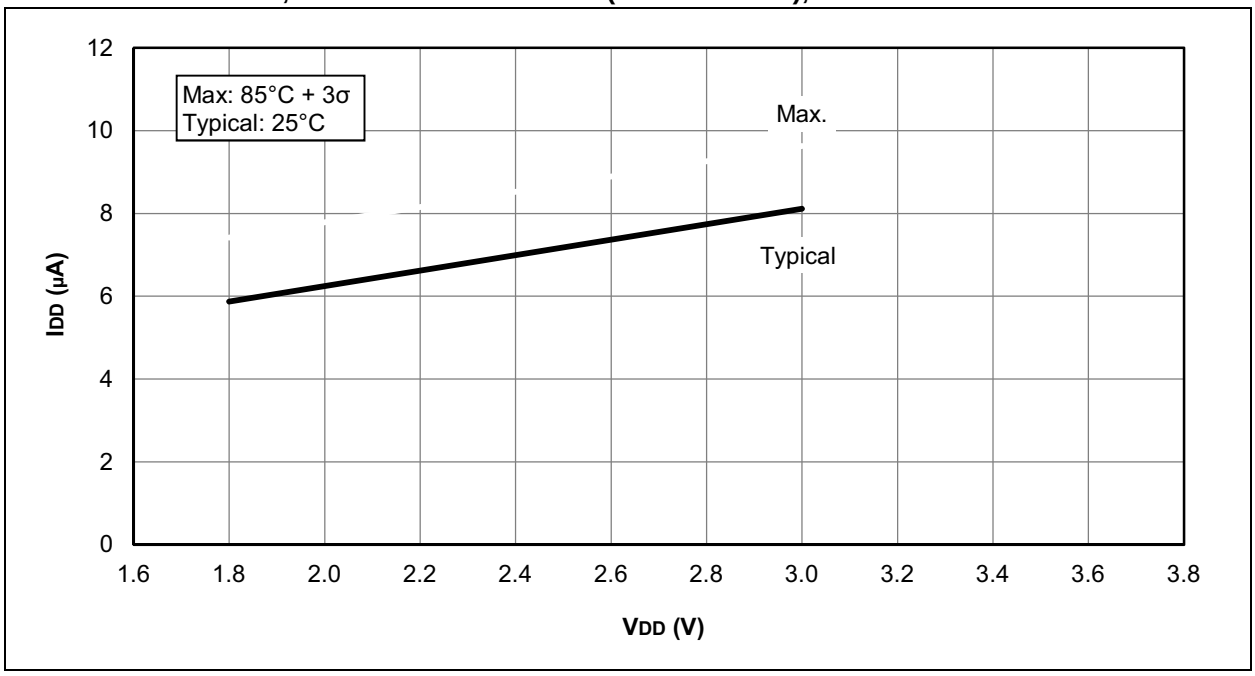


FIGURE 31-2: IDD, LP OSCILLATOR MODE (FOSC = 32 kHz), PIC16F1825/9 ONLY

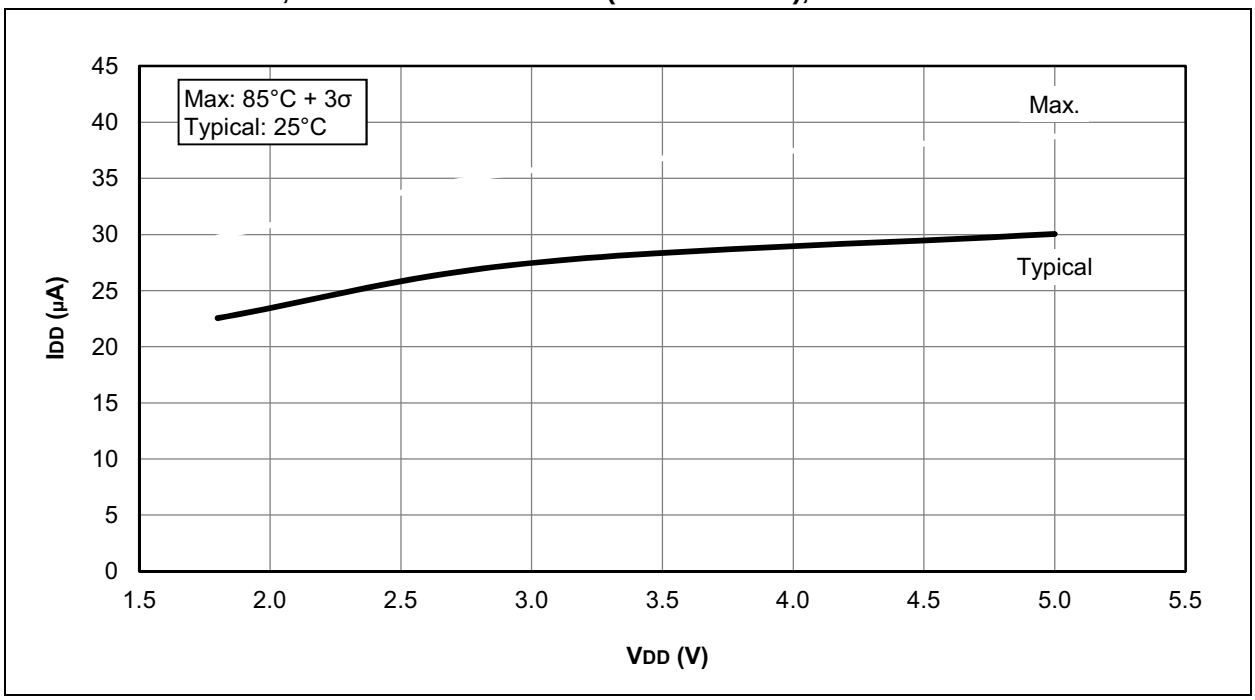


FIGURE 31-35: IPD, CAPACITIVE SENSING (CPS) MODULE, HIGH-CURRENT RANGE, CPSRM = 0, PIC16LF1825/9 ONLY

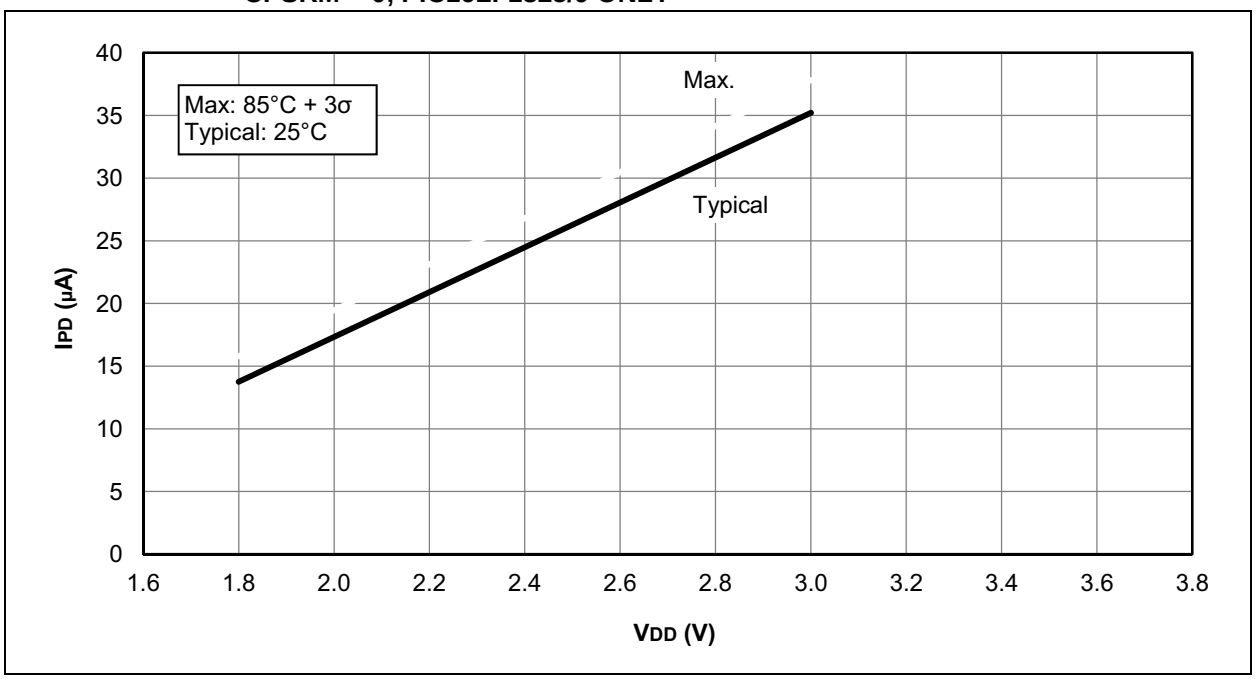
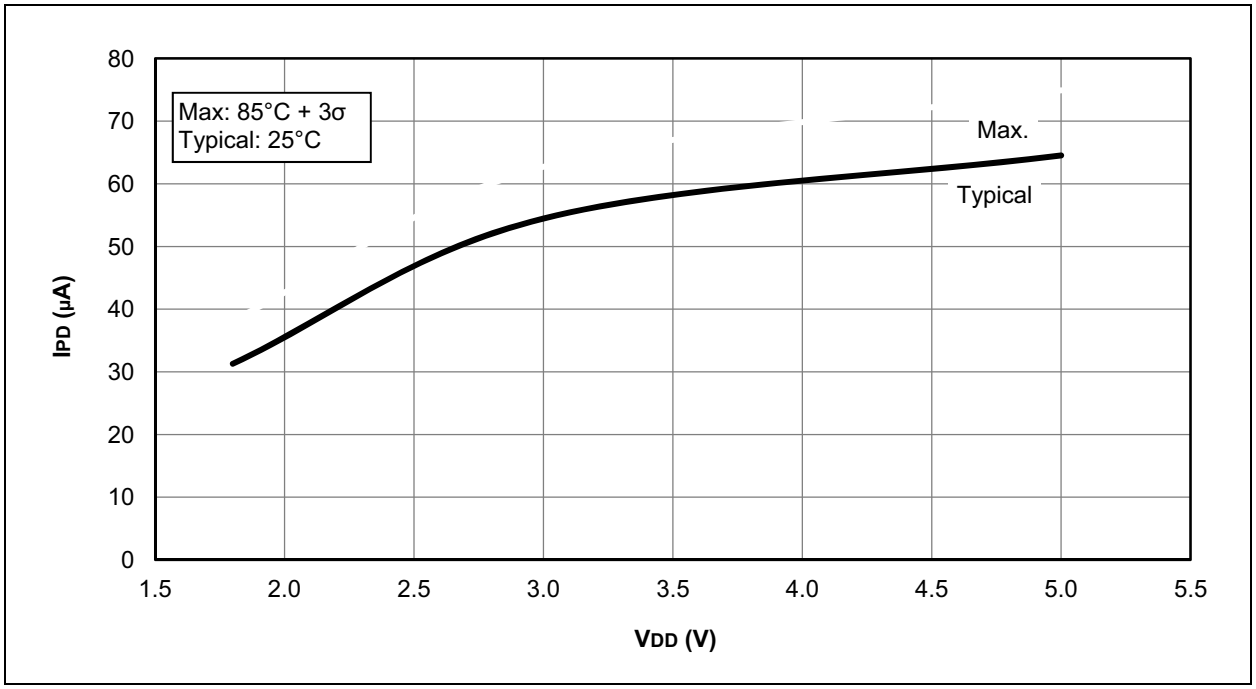
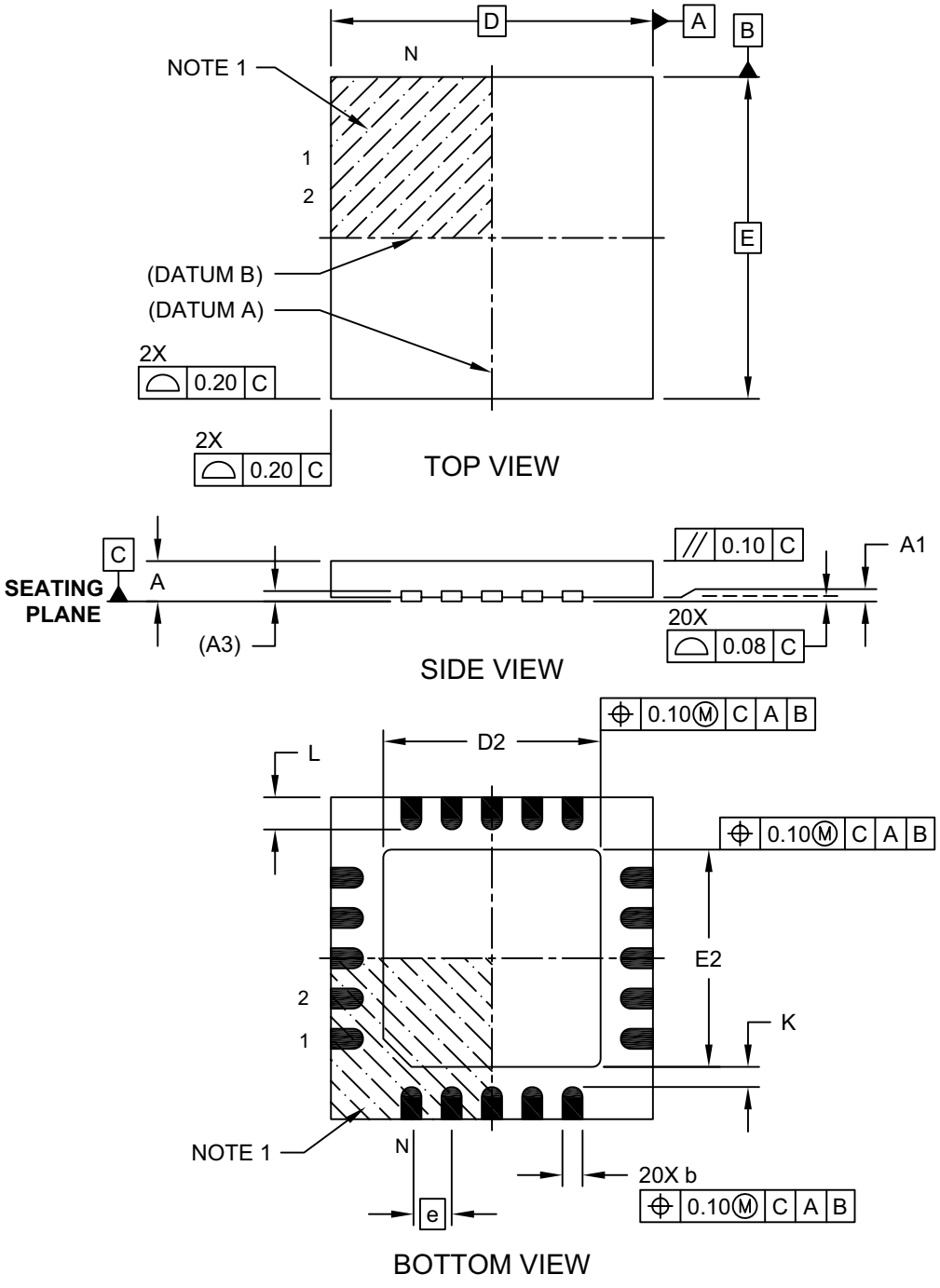


FIGURE 31-36: IPD, CAPACITIVE SENSING (CPS) MODULE, HIGH-CURRENT RANGE, CPSRM = 0, PIC16F1825/9 ONLY



20-Lead Ultra Thin Plastic Quad Flat, No Lead Package (GZ) - 4x4x0.5 mm Body [UQFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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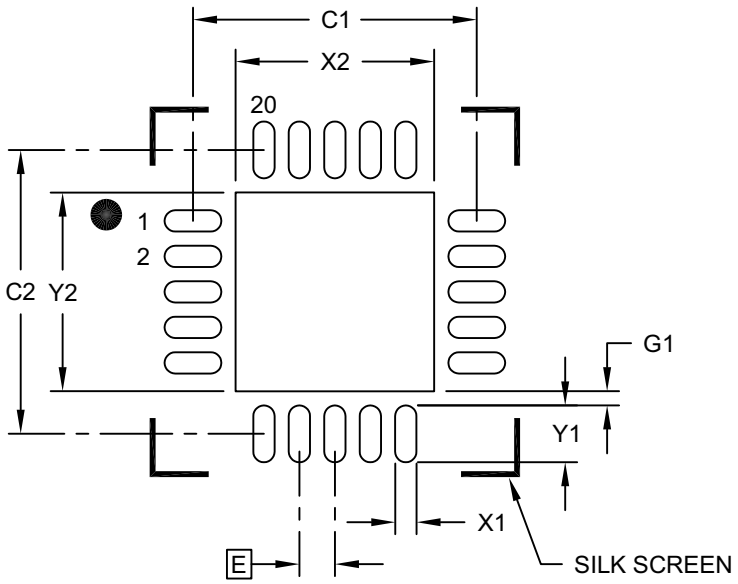
20-Lead Ultra Thin Plastic Quad Flat, No Lead Package (GZ) - 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	X2			2.80
Optional Center Pad Length	Y2			2.80
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X20)	X1			0.30
Contact Pad Length (X20)	Y1			0.80
Contact Pad to Center Pad (X20)	G1	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

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